Overview

HP 340 G7 Notebook PC

Left

1. Internal Microphones (2)
2. Webcam LED
3. Webcam
4. Touchpad
5. Touchpad Button
6. Power Indicator LED

7. Hard Drive Indicator LED
8. SD Card Slot
9. USB Type-C™ 3.1 Gen Port
10. USB 3.1 Gen 1 Port
11. Security Lock Slot (Lock sold separately)
12. Power Button

Not all configuration components are available in all regions/countries.
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Overview

Right

1. Power Connector
2. RJ-45/Ethernet Port
3. HDMI Port (Cable not included.)

4. USB 3.1 Gen 1 Port
5. USB 3.1 Gen 1 Port
6. Audio Combo Jack

Not all configuration components are available in all regions/countries.
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Overview

AT A GLANCE

- Preinstall with Windows 10 or FreeDOS
- Choice of 10th Generation Intel® Core™ i7, i5 and i3 processors
- Display include your choice of 35.56 cm (14") diagonal narrow bezel, AntiGlare, ultra-wide or standard view angle, HD or FHD
- Graphics include your choice of integrated Intel® graphics or switchable discrete graphics AMD Radeon™ 530
- Enhanced security features including Hardware TPM, Fingerprint Sensor[2] (select models), and security lock slot
- Passed 120,000 hours of reliability testing through HP's Total Test Process
- Integrated with 2 stereo speakers and dual array microphone for better audio experience
- Support dual storage, Solid State Drives up to 512 GB, and/or HDDs up to 1 TB
- Up to 32 GB total system memory
- Offers 720p HD webcam or no webcam edition for your options
- Full-size island-style, spill resistant keyboard and Touchpad with multi-touch gestures enabled, taps enabled as default
- Passed 13 MIL-STD 810G tests[1]

1. MIL-STD-810G testing is not intended to demonstrate fitness of U.S. Department of Defense (DoD) contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.
2. HP Fingerprint Sensor is an optional feature and requires configuration at purchase.

NOTE: See important legal disclosures for all listed specs in their respective features sections.

Not all configuration components are available in all regions/countries.   Page 3

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PRODUCT NAME

HP 340 G7 Notebook PC

OPERATING SYSTEM

Preinstalled

Windows 10 Pro 64[1]
Windows 10 Home 64[1]
Windows 10 Home Single Language 64[1]
Windows 10 Pro (Windows 10 Enterprise available with a Volume Licensing Agreement)[1]
FreeDOS[1]

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

PROCESSOR

Intel® Celeron® processors
Intel® Core™ i7-10510U processor with Intel® UHD Graphics (1.8 GHz base frequency, up to 4.9 GHz with Intel® Turbo Boost Technology, 8 MB L3 cache, 4 cores)[3,4,5,6]
Intel® Core™ i5-10210U processor with Intel® UHD Graphics (1.6 GHz base frequency, up to 4.2 GHz with Intel® Turbo Boost Technology, 6 MB L3 cache, 4 cores) [3,4,5,6]
Intel® Core™ i3-10110U processor with Intel® UHD Graphics (2.1 GHz base frequency, up to 4.1 GHz with Intel® Turbo Boost Technology, 4 MB L3 cache, 2 cores) [3,4,5,6]
Intel® Core™ i3-8130U with Intel® UHD Graphics 620 (2.2 GHz base frequency, up to 3.4 GHz with Intel® Turbo Boost Technology, 4 MB L3 cache, 2 cores) [3,4,5,6]
Intel® Core™ i3-7020U with Intel® HD Graphics 620 (2.3 GHz, 3 MB L3 cache, 2 cores)[3,4,6]

Processor Family
10th Generation Intel® Core™ i7 processor (i7-10510U)[7]
10th Generation Intel® Core™ i5 processor (i5-10210U) [7]
10th Generation Intel® Core™ i3 processor (i3-10110U) [7]
8th Generation Intel® Core™ i3 processor (i3-8130U) [7]
7th Generation Intel® Core™ i3 processor (i3-7020U) [7]

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CHIPSET

Chipset is integrated with processor

GRAPHICS

Integrated
Intel® UHD Graphics (i7-10510U, i5-10210U, and i3-10110U)[8]
Intel® UHD Graphics 620 (i3-8130U)[8]
Intel® HD Graphics 620 (i3-7020U)[8]
NOTE: See processor section for details.

Discrete
AMD Radeon™ 530 (2 GB GDDR5 dedicated)[9]

Supports
Support HD decode, DX12, HDMI 1.4

8. HD content required to view HD images.
9. AMD Dynamic Switchable Graphics technology requires an Intel processor, plus an AMD Radeon™ discrete graphics configuration and is not available on FreeDOS and Linux OS. With AMD Dynamic Switchable Graphics technology, full enablement of all discrete graphics video and display features may not be supported on all systems (e.g. OpenGL applications will run on the integrated GPU or the APU as the case may be).

DISPLAY

Non-Touch
35.56 cm (14") diagonal HD SVA eDP anti-glare WLED-backlit slim-flat, 220 nits, 45% NTSC, one WLAN antenna (1366 x 768)[8,10]
35.56 cm (14") diagonal HD SVA eDP anti-glare WLED-backlit slim-flat, 220 nits, 45% NTSC, two WLAN antennas (1366 x 768) [8,10]
35.56 cm (14") diagonal FHD, UWVA IPS eDP anti-glare WLED-backlit slim-flat, 250 nits, 45% NTSC, one WLAN antenna (1920 x 1080) [8,10]
35.56 cm (14") diagonal FHD UWVA IPS eDP anti-glare WLED-backlit slim-flat, 250 nits, 45% NTSC, two WLAN antennas (1920 x 1080) [8,10]

8. HD content required to view HD images.
10. Resolutions are dependent upon monitor capability, and resolution and color depth settings.

STORAGE AND DRIVES

Primary Storage
500 GB 7200 rpm SATA[11]
1 TB 5400 rpm SATA[11]

Primary M.2 Storage
128 GB SATA TLC Solid State Drive[11]
256 GB PCIe® NVMe™ Value Solid State Drive[11]
256 GB PCIe® NVMe™ TLC Solid State Drive[11]

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512 GB PCIe® NVMe™ Value Solid State Drive[11]

Cache Memory
Intel® Optane™ 16 GB Cache[12]
Only available with HDD

11. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.
12. Intel® Optane™ memory is sold separately. Intel® Optane™ memory system acceleration does not replace or increase the DRAM in your system. Available for HP commercial desktops and notebooks and for select HP workstations (HP Z240 Tower/SFF, Z2 Mini, ZBook Studio, 15 and 17 G5) and requires a SATA HDD, 7th Gen or higher Intel® Core™ processor or Intel® Xeon® processor E3-1200 V6 product family or higher, BIOS version with Intel® Optane™ supported, Windows 10 version 1703 or higher, M.2 type 2280-S1-B-M connector on a PCH Remapped PCIe Controller and Lanes in a x2 or x4 configuration with B-M keys that meet NVMe™ Spec 1.1, and an Intel® Rapid Storage Technology (Intel® RST) 15.5 driver.

MEMORY

Maximum Memory
32 GB DDR4-2666 SDRAM (only available for 10th Generation Intel® processors)
32 GB DDR4-2133 SDRAM[13]

Memory
32 GB DDR4-2666 SDRAM (2 X 16 GB) (Only available for 10th Generation Intel® processors)[13]
16 GB DDR4-2666 SDRAM (1 X 16 GB) (Only available for 10th Generation Intel® processors)[13]
8 GB DDR4-2666 SDRAM (1 x 8 GB) (Only available for 10th Generation Intel® processors)[13]
4 GB DDR4-2666 SDRAM (1 x 4 GB) (Only available for 10th Generation Intel® processors)[13]
32 GB DDR4-2133 SDRAM (2 X 16 GB)[13]
16 GB DDR4-2133 SDRAM (1 X 16 GB)[13]
8 GB DDR4-2133 SDRAM (1 x 8 GB)[13]
4 GB DDR4-2133 SDRAM (1 x 4 GB)[13]

Memory Slots
2 SODIMM
Both slots are customer accessible / upgradeable
DDR4 PC4 SODIMMS runs at 2666 on 10th Gen Intel® (CML) processors and runs at 2133 on 8th/7th Gen Intel (KBL and KBL-R) processors
Supports Dual Channel Memory

13. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

Not all configuration components are available in all regions/countries.
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NETWORKING/COMMUNICATIONS

WLAN
Realtek 802.11a/b/g/n/ac (1x1) and Bluetooth® 4.2 Combo[14]
Realtek 802.11a/b/g/n/ac (2x2) and Bluetooth® 5 Combo[14]
Intel® Dual Band Wireless-AC 9560 802.11a/b/g/n/ac (2x2) Wi-Fi® and Bluetooth® 5 Combo, non-vPro™[14,15]
Intel® Dual Band Wi-Fi 6 AX201 802.11a/b/g/n/ac/ax (2x2) WLAN and Bluetooth® 5 Combo, non-vPro™[15]*

Miracast
Support for Miracast[16]

Ethernet
Integrated 10/100/1000 GbE
Realtek RTL8111HSH-CG 10/100/1000 GbE NIC[17]

14. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited.
15. Only available for 10th Generation Intel® processors
16. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.
17. The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.
*Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices. Only available in countries where 802.11ax is supported

AUDIO/MULTIMEDIA

Audio
2 Integrated Stereo Speakers
Integrated Dual Array Microphone

Camera
HP TrueVision HD Camera[8,18]

8. HD content required to view HD images.
18. Sold separately or as an optional feature.

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard
Full size island-style spill-resistant keyboard

Pointing Device
Touchpad with multi-touch gesture support

Not all configuration components are available in all regions/countries.
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Function Keys
ESC: System Information
F1: Windows Help
F2: Brightness Down
F3: Brightness Up
F4: Display Switching
F5: Blank
F6: Speaker Mute
F7: Volume Down
F8: Volume Up
F9: Previous track/section
F10: Starts, Pauses, or resumes playback
F11: Next track/section
F12: Airplane mode (Wireless feature on or off).

SOFTWARE AND SECURITY

Software

HP Support Assistant[19]
Native Miracast Support[20]

Security Management
Security Lock
HP Drivelock[21]
Hardware TPM and Firmware TPM 2.0
Fingerprint Sensor (select models)[22]

19. HP Support Assistant requires Windows and Internet access.
20. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.
21. Supports primary storage only
22. HP Fingerprint Sensor is an optional feature and requires configuration at purchase.

POWER

Power Supply

HP Smart 65 W EM External AC power adapter[23]

Primary Battery
HP Long Life 3-cell, 41 Wh Li-ion[24]
Support HP fast charge technology[25]

Power Cord
3-wire plug – 1 m[23]

Battery Life
Up to 13 hours (UMA, CML-U processor, HD display, 4 GB*1 memory, SSD)[26]

Not all configuration components are available in all regions/countries.
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Battery Weight
0.19 lb
0.41 kg

23. Availability may vary by country.
24. Battery is internal and not replaceable by customer. Serviceable by warranty.
25. Recharges the battery up to 90% within 90 minutes or up to 50% within 45 minutes when the system is off or in standby mode. Power adapter with a minimum capacity of 65 watts is required. After charging has reached 50% capacity, charging will return to normal. Charging time may vary +/-10% due to System tolerance.
26. Windows 10 MM14 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See http://www.bapco.com for additional details.

WEIGHTS & DIMENSIONS

Product Weight
Starting at 3.3 lbs[27]
Starting at 1.5 kg[27]
Does not include power adapter.

Product Dimensions (W x D x H)
8.89 x 12.76 x 0.783 in
22.59 x 32.4 x 1.99 cm

27. Weight will vary by configuration.

PORTS/SLOTS

Ports
1 USB type C (support USB3.1 gen1 /data-transfer only)
2 USB 3.1 gen 1
1 USB 3.1 gen 1 (support charging/power delivery)
1 HDMI 1.4[28]
1 RJ-45
1 AC power
1 Headphone/microphone combo jack

Expansion Slots
1 multi-format digital media reader
Supports SD, SDHC, SDXC

28. HDMI cable sold separately.

SERVICE AND SUPPORT

HP Services offers 1-year limited warranties and 90 day software limited warranty options depending on country. Refer to http://www.hp.com/support/batterywarranty/ for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at:

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http://www.hp.com/go/cpc.[29]

29. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

SYSTEM UNIT

Stand-Alone Power Requirements (AC Power)	**Nominal Operating Voltage**	19.5 V
	Average Operating Power	Win 10
	Integrated Graphics	5.28 W
	Max Operating Power	Discrete < 65W UMA < 45W
Temperature	**Operating**	32° to 95° F (0° to 35° C) (not writing optical) 41° to 95° F (5° to 35° C) (writing optical)
	Non-operating	-4° to 140° F (-20° to 60° C)
Relative Humidity	**Operating**	10% to 90%, non-condensing
	Non-operating	5% to 95%
Shock	**Operating**	40 G, 2 ms duration, half-sine
	Non-operating	240 G, 2 ms duration, half-sine
Random Vibration	**Operating**	1.043 grms
	Non-operating	3.5 grms
Altitude (unpressurized)	**Operating**	-15 m to 3048 m (-50 ft to 10000 ft)
	Non-operating	-15 m to 12192 m (-50 ft to 40000 ft)
Planned Industry Standard Certifications	**UL**	Yes
	CSA	No
	FCC Compliance	Yes
	ENERGY STAR®	No, but compliant with ENERGY STAR[30]
	EPEAT®	EPEAT® 2019 Silver in U.S.[31]
	ICES	Yes
	Australia	No
	NZ A-Tick Compliance	No
	CCC	Yes
	Japan VCCI Compliance	No
	KC	No
	BSMI	Yes
	CE Marking Compliance	Yes
	BNCI or BELUS	No
	CIT	No
	GOST	No
	Saudi Arabian Compliance (ICCP)	No
	SABS	No

Not all configuration components are available in all regions/countries.

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UKRSERTCOMPUTER	No

30. Configurations of the HP 340 Notebook PC that are ENERGY STAR® certified are identified as HP 340 Notebook PC ENERGY STAR® on HP websites and on http://www.energystar.gov.

31. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit http://www.epeat.net for more information.

DISPLAYS

Note: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

14 inch diagonal FHD WLED Anti-Glare (1920 x 1080) slim-flat (3.0 mm), UWVA, eDP, Narrow Bezel	Outline Dimensions (W x H x D)	320.9 x 205.6 (max)
	Active Area	309.31 x 173.99
	Weight	290g (max)
	Diagonal Size	14 inch
	Thickness	3.0 mm max.
	Interface	eDP 1.2 (2 Lane)
	Surface Treatment	Anti-Glare (AG)
	Touch Enabled	No
	Contrast Ratio	600:1 (typ)
	Refresh Rate	60 Hz
	Brightness	250 nit typ
	Pixel Resolution	1920 x 1080 (FHD)
	Format of LCD Pixel Arrangement	RGB
	Backlight	LED
	Color Gamut Coverage	45% of NTSC
	Color Depth	6 bits
	Viewing Angle	UWVA 85/85/85/85

14 inch diagonal HD SVALED-backlight; 220 cd/m2; 45% sRGB (1366 x 768)	Outline Dimensions (W x H x D)	316.2 x 198 (mm) max (with PCB Board)
	Active Area	309.4 x 173.95 (mm)
	Weight	280 g max.
	Diagonal Size	14.0 (inch)
	Thickness	3.0 (mm) max
	Interface	eDP 1.2
	Surface Treatment	Anti-glare (AG)
	Touch Enabled	None
	Contrast Ratio	500:1 (typical)
	Refresh Rate	60 Hz
	Brightness	220 nit typical

Not all configuration components are available in all regions/countries.
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	Pixel Resolution	1366 x 768 (HD)
	Format of LCD Pixel Arrangement	RGB
	Backlight	LED
	Color Gamut Coverage	45% of NTSC
	Color Depth	6 bits
	Viewing Angle	45/45/20/45

STORAGE AND DRIVES

500 GB 7200 rpm SATA Hard Drive	**Drive Weight**	0.21 lbs (95 g)
	Rotation speed	7200 rpm
	Cache Buffer	Up to 128MB
	Height	0.28 in (7 mm)
	Width	2.75 in (69.85 mm)
	Interface	ATA-8, SATA 3.0
	Transfer Rate	600 MB/s
	Seek Time	Single Track: 2 ~ 1.5 ms Average: 11 ~ 13 ms Maximum: 18 ~ 22 ms
	Logical Blocks	976,773,168
	Operating Temperature	32° to 140° F (0° to 60° C) [case temp]
	Security Features	ATA Security
	Features	S.M.A.R.T., NCQ, Ultra DMA

1 TB 5400 rpm SATA Hard Drive	**Drive Weight**	0.21 lbs (94 g)- 0.21 lbs (95 g)
	Rotation speed	5400 rpm
	Cache Buffer	Up to 128MB
	Height	0.28 in (7 mm)
	Width	2.75 in (69.85 mm)
	Interface	ATA-8, SATA 3.0
	Transfer Rate	600 MB/s
	Seek Time	Single Track: 2ms; Average: 12 ~ 13 ms; Maximum: 18 ~ 22 ms
	Logical Blocks	1,953,525,168
	Operating Temperature	32° to 140° F (0° to 60° C) [case temp]
	Security Features	ATA Security
	Features	S.M.A.R.T., NCQ, Ultra DMA

Not all configuration components are available in all regions/countries.
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128 GB 2280 M2 SATA-3 TLC Solid State Drive		
	Drive Weight	M.2 2280
	Rotation speed	128 GB
	Cache Buffer	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Interface	0.01 lb (6 g) ~ 0.02 lb (10 g)
	Transfer Rate	ATA-8, SATA 3.0
	Seek Time	Up To 535 MB/s
	Logical Blocks	Up To 515 MB/s
	Operating Temperature	250,069,680
	Security Features	32° to 158°F (0° to 70°C) [ambient temp]
	Features	DIPM; TRIM; DEVSLP

256 GB 2280 M2 PCIe NVMe Value Solid State Drive		
	Form Factor	M.2 2280
	Capacity	256GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Interface	PCIe NVMe Gen3x2
	Maximum Sequential Read	Up to 1500 MB/s
	Maximum Sequential Write	Up to 1000 MB/s
	Logical Blocks	500,118,192
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	TRIM, L1.2

256 GB PCIe NVMe TLC Solid State Drive		
	Form Factor	M.2 2280
	Capacity	256 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Interface	PCIe NVMe Gen3x4
	Maximum Sequential Read	Up to 2500 MB/s
	Maximum Sequential Write	Up to 1000 MB/s
	Logical Blocks	500,118,192
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]

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	Features	TRIM, L1.2

512 GB 2280 M2 PCIe NVMe Value Solid State Drive	**Form Factor**	M.2 2280
	Capacity	512 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.01 lb (6 g) ~ 0.02 lb (10 g)
	Interface	PCIe NVMe Gen3x2
	Maximum Sequential Read	Up to 1500 MB/s
	Maximum Sequential Write	Up to 1000 MB/s
	Logical Blocks	1,000,215,215
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	TRIM, L1.2

NETWORKING/COMMUNICATIONS

Intel® 9560 802.11a/b/g/n/ac (2 x 2) Wi-Fi® and Bluetooth® 5.0 Combo[1] non-vPro	**Wireless LAN Standards**	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
	Interoperability	Wi-Fi certified modules

	Frequency Band	•802.11b/g/n
		  2.402 – 2.482 GHz
		•802.11a/n/ac
		  4.9 – 4.95 GHz (Japan)
		  5.15 – 5.25 GHz
		  5.25 – 5.35 GHz
		  5.47 – 5.725 GHz
		  5.825 – 5.850 GHz

	Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps

Not all configuration components are available in all regions/countries.
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	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) • 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz & 160MHz)
Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security[3]	• IEEE and WiFi certified 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • IEEE 802.11i • WAPI
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power[2]	• 802.11b: +18.5dBm minimum • 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum • 802.11n HT20(2.4GHz): +15.5dBm minimum • 802.11n HT40(2.4GHz): +14.5dBm minimum • 802.11n HT20(5GHz): +15.5dBm minimum • 802.11n HT40(5GHz): +14.5dBm minimum • 802.11ac VHT80(5GHz): +11.5dBm minimum • 802.11ac VHT160(5GHz): +11.5dBm minimum
Power Consumption	• Transmit mode: 2.0 W • Receive mode: 1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode: 50 mW (WLAN unassociated) • Connected Standby/Modern Standby: 10mW • Radio disabled: 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity [3]	• 802.11b, 1Mbps: -93.5dBm maximum • 802.11b, 11Mbps: -84dBm maximum • 802.11a/g, 6Mbps: -86dBm maximum • 802.11a/g, 54Mbps: -72dBm maximum • 802.11n, MCS07: -67dBm maximum • 802.11n, MCS15: -64dBm maximum • 802.11ac, MCS0: -84dBm maximum • 802.11ac, MCS9: -59dBm maximum
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications

Not all configuration components are available in all regions/countries.

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Form Factor	PCI-Express M.2 MiniCard with CNVi Interface	
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm	
Weight	1. Type 2230: 2.8 g 2. Type 126: 1.3 g	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating	14° to 158° F (−10° to 70° C)
	Non-operating	−40° to 176° F (−40° to 80° C)
Humidity	Operating	10% to 90% (non-condensing)
	Non-operating	5% to 95% (non-condensing)
Altitude	Operating	0 to 10,000 ft (3,048 m)
	Non-operating	0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF LED White – Radio ON	

1. Check latest software/driver release for updates on supported security features.
2. Maximum output power may vary by country according to local regulations.
3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0 Wireless Technology

Bluetooth Specification	4.0/4.1/4.2/5.0 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Signaling Data Rate	Legacy: 3 Mbps signaling data rate[1] 2.17 Mbps BLE: 1 Mbps signaling data rate[1] 0.2 Mbps 1. Actual throughput may vary. Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW

Not all configuration components are available in all regions/countries.
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Bluetooth Software Supported Link Topology	Microsoft Windows Bluetooth Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

Intel® Wi-Fi 6[4] AX201 + Bluetooth® 5 (802.11 a/b/g/n/ac/ax 2 x 2, non-vPro, supporting gigabit file transfer speeds) non-vPro	**Wireless LAN Standards**	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
	Interoperability	Wi-Fi modules
	Frequency Band	•802.11b/g/n/ax 2.402 – 2.482 GHz •802.11a/n/ac/ax 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz

Not all configuration components are available in all regions/countries.
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	5.25 – 5.35 GHz
	5.47 – 5.725 GHz
	5.825 – 5.850 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
	• 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz & 160MHz)
	• 802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, 80MHz & 160MHz)
Modulation	Direct Sequence Spread Spectrum
	OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
Security[3]	• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only
	• AES-CCMP: 128 bit in hardware
	• 802.1x authentication
	• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
	• WPA2 certification
	• IEEE 802.11i
	• WAPI
Network Architecture Models	Ad-hoc (Peer to Peer)
	Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power[2]	• 802.11b: +18.5dBm minimum
	• 802.11g: +17.5dBm minimum
	• 802.11a: +18.5dBm minimum
	• 802.11n HT20(2.4GHz): +15.5dBm minimum
	• 802.11n HT40(2.4GHz): +14.5dBm minimum
	• 802.11n HT20(5GHz): +15.5dBm minimum
	• 802.11n HT40(5GHz): +14.5dBm minimum
	• 802.11ac VHT80(5GHz): +11.5dBm minimum
	• 802.11ac VHT160(5GHz): +11.5dBm minimum
	• 802.11ax HT40(2.4GHz): +10dBm minimum
	• 802.11ax VHT160(5GHz): +10dBm minimum
Power Consumption	• Transmit mode: 2.0 W
	• Receive mode: 1.6 W
	• Idle mode (PSP) 180 mW (WLAN Associated)
	• Idle mode: 50 mW (WLAN unassociated)
	• Connected Standby/Modern Standby: 10mW
	• Radio disabled: 8 mW
Power Management	ACPI and PCI Express compliant power management
	802.11 compliant power saving mode
Receiver Sensitivity [3]	•802.11b, 1Mbps: -93.5dBm maximum
	•802.11b, 11Mbps: -84dBm maximum
	• 802.11a/g, 6Mbps: -86dBm maximum

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- 802.11a/g, 54Mbps: -72dBm maximum
- 802.11n, MCS07: -67dBm maximum
- 802.11n, MCS15: -64dBm maximum
- 802.11ac, MCS0: -84dBm maximum
- 802.11ac, MCS9: -59dBm maximum
- 802.11ax, MCS11(HT40): -59dBm maximum
- 802.11ax, MCS11(VHT160): -58.5dBm maximum

Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm
Weight	1. Type 2230: 2.8 g 2. Type 126: 1.3 g
Operating Voltage	3.3v +/- 9%

Temperature	Operating	14° to 158° F (−10° to 70° C)
	Non-operating	−40° to 176° F (−40° to 80° C)
Humidity	Operating	10% to 90% (non-condensing)
	Non-operating	5% to 95% (non-condensing)
Altitude	Operating	0 to 10,000 ft (3,048 m)
	Non-operating	0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF	
	LED Off – Radio ON	

1. Check latest software/driver release for updates on supported security features.
2. Maximum output power may vary by country according to local regulations.
3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).
4. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices. Only available in countries where 802.11ax is supported.

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

Bluetooth Specification	4.0/4.1/4.2/5.0/5.1 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)

Not all configuration components are available in all regions/countries.

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Signaling Data Rate	Legacy: 3 Mbps signaling data rate[1] 2.17 Mbps	
	BLE: 1 Mbps signaling data rate[1] 0.2 Mbps	
	1. Actual throughput may vary.	
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels	
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)	
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.	
Power Consumption	Peak (Tx) 330 mW	
	Peak (Rx) 230 mW	
	Selective Suspend 17 mW	
Bluetooth Software Supported Link Topology	Microsoft Windows Bluetooth Software	
Power Management	Microsoft Windows ACPI, and USB Bus Support	
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249	
Power Management Certifications	ETS 300 328, ETS 300 826	
	Low Voltage Directive IEC950	
	UL, CSA, and CE Mark	
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance	
	LE Link Layer Ping	
	LE Dual Mode	
	LE Link Layer	
	LE Low Duty Cycle Directed Advertising	
	LE L2CAP Connection Oriented Channels	
	Train Nudging & Interlaced Scan	
	BT4.2 ESR08 Compliance	
	LE Secure Connection- Basic/Full	
	LE Privacy 1.2 –Link Layer Privacy	
	LE Privacy 1.2 –Extended Scanner Filter Policies	
	LE Data Packet Length Extension	
	FAX Profile (FAX)	
	Basic Imaging Profile (BIP)2	
	Headset Profile (HSP)	
	Hands Free Profile (HFP)	
	Advanced Audio Distribution Profile (A2DP)	

802.11a/b/g/n/ac (1 x 1) Wi-Fi® and Bluetooth® 4.2 Combo[1]	**Wireless LAN Standards**	IEEE 802.11a
		IEEE 802.11b
		IEEE 802.11g
		IEEE 802.11n

Not all configuration components are available in all regions/countries.

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	IEEE 802.11ac
	IEEE 802.11d
	IEEE 802.11e
	IEEE 802.11h
	IEEE 802.11i
	IEEE 802.11k
	IEEE 802.11r
	IEEE 802.11v
Interoperability	Wi-Fi CERTIFIED™

Frequency Band	•802.11b/g/n
	  2.402 – 2.482 GHz
	•802.11a/n/ac
	  4.9 – 4.95 GHz (Japan)
	  5.15 – 5.25 GHz
	  5.25 – 5.35 GHz
	  5.47 – 5.725 GHz
	  5.825 – 5.850 GHz

Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) • 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)
Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security[3]	• IEEE 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • IEEE 802.11i • WAPI
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power[2]	• 802.11b: +14dBm minimum • 802.11g: +12dBm minimum • 802.11a: +12dBm minimum • 802.11n HT20(2.4GHz): +12dBm minimum • 802.11n HT40(2.4GHz): +12dBm minimum • 802.11n HT20(5GHz): +10dBm minimum • 802.11n HT40(5GHz): +10dBm minimum • 802.11ac VHT80(5GHz): +10dBm minimum
Power Consumption	• Transmit mode: 2.0 W • Receive mode: 1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode: 50 mW (WLAN unassociated)

Not all configuration components are available in all regions/countries.
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	• Connected Standby: 10mW • Radio disabled: 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity ³	• 802.11b, 1Mbps: -93.5dBm maximum • 802.11b, 11Mbps: -84dBm maximum • 802.11a/g, 6Mbps: -86dBm maximum • 802.11a/g, 54Mbps: -72dBm maximum • 802.11n, MCS07: -67dBm maximum • 802.11n, MCS15: -64dBm maximum • 802.11ac, MCS0: -84dBm maximum • 802.11ac, MCS9: -59dBm maximum
Antenna type	High efficiency antenna. One embedded dual band 2.4/5 GHz antenna is provided to the card to support WLAN communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard
Dimensions	Type 2230: 2.3 x 22.0 x 30.0 mm
Weight	Type 2230: 2.8 g
Operating Voltage	3.3v +/- 9%

Temperature	Operating	14° to 158° F (−10° to 70° C)
	Non-operating	−40° to 176° F (−40° to 80° C)
Humidity	Operating	10% to 90% (non-condensing)
	Non-operating	5% to 95% (non-condensing)
Altitude	Operating	0 to 10,000 ft (3,048 m)
	Non-operating	0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF LED Off – Radio ON	

1. Check latest software/driver release for updates on supported security features.
2. Maximum output power may vary by country according to local regulations.
3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

HP Integrated Module with Bluetooth 4.0/4.1/4.2 Wireless Technology

Bluetooth Specification	4.0/4.1/4.2 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Signaling Data Rate	Legacy: 3 Mbps signaling data rate[1] 2.17 Mbps BLE: 1 Mbps signaling data rate[1] 0.2 Mbps 1. Actual throughput may vary.

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		Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels
		Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
	Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
	Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
	Bluetooth Software Supported **Link Topology**	Microsoft Windows Bluetooth Software
	Power Management	Microsoft Windows ACPI, and USB Bus Support
	Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
	Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
	Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)
RTL8822CE **802.11a/b/g/n/ac 2 x 2** **Wi-Fi® and Bluetooth® 5**	**Wireless LAN Standards**	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11d IEEE 802.11e IEEE 802.11h

Not all configuration components are available in all regions/countries.
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Technical Specifications

	IEEE 802.11i
	IEEE 802.11k
	IEEE 802.11r
	IEEE 802.11v
Interoperability	Wi-Fi CERTIFIED®

Frequency Band	• 802.11b/g/n
	   2.402 – 2.482 GHz
	• 802.11a/n/ac
	   4.9 – 4.95 GHz (Japan)
	   5.15 – 5.25 GHz
	   5.25 – 5.35 GHz
	   5.47 – 5.725 GHz
	   5.825 – 5.850 GHz

Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) • 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz & 80MHz)
Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security[3]	• IEEE 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • IEEE 802.11i • WAPI
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power[2]	• 802.11b: +18.5dBm minimum • 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum • 802.11n HT20(2.4GHz): +15.5dBm minimum • 802.11n HT40(2.4GHz): +14.5dBm minimum • 802.11n HT20(5GHz): +15.5dBm minimum • 802.11n HT40(5GHz): +14.5dBm minimum • 802.11ac VHT80(5GHz): +11.5dBm minimum • 802.11ac VHT160(5GHz): +11.5dBm minimum
Power Consumption	• Transmit mode: 2.0 W • Receive mode: 1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode: 50 mW (WLAN unassociated) • Connected Standby/Modern Standby: 10mW • Radio disabled: 8 mW
Power Management	ACPI and PCI Express compliant power management

Not all configuration components are available in all regions/countries.
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	802.11 compliant power saving mode
Receiver Sensitivity [3]	• 802.11b, 1Mbps: -93.5dBm maximum
	• 802.11b, 11Mbps: -84dBm maximum
	• 802.11a/g, 6Mbps: -86dBm maximum
	• 802.11a/g, 54Mbps: -72dBm maximum
	• 802.11n, MCS07: -67dBm maximum
	• 802.11n, MCS15: -64dBm maximum
	• 802.11ac, MCS0: -84dBm maximum
	• 802.11ac, MCS9: -59dBm maximum
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure
	Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm
	2. Type 1216: 1.67 x 12.0 x 16.0 mm
Weight	1. Type 2230: 2.8 g
	2. Type 126: 1.3 g
Operating Voltage	3.3v +/- 9%

Temperature	Operating	14° to 158° F (−10° to 70° C)
	Non-operating	−40° to 176° F (−40° to 80° C)
Humidity	Operating	10% to 90% (non-condensing)
	Non-operating	5% to 95% (non-condensing)
Altitude	Operating	0 to 10,000 ft (3,048 m)
	Non-operating	0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF	
	LED OFF – Radio ON	

1. Check latest software/driver release for updates on supported security features.
2. Maximum output power may vary by country according to local regulations.
3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

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Bluetooth Specification	4.0/4.1/4.2/5.0 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH)
	BLE: 0~39 (2 MHz/CH)
Signaling Data Rate	Legacy: 3 Mbps signaling data rate[1] 2.17 Mbps
	BLE: 1 Mbps signaling data rate[1] 0.2 Mbps
	1. Actual throughput may vary.

Not all configuration components are available in all regions/countries.

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	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels	
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)	
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.	
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW	
Bluetooth Software Supported **Link Topology**	Microsoft Windows Bluetooth Software	
Power Management	Microsoft Windows ACPI, and USB Bus Support	
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249	
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark	
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)	

POWER

HP 45 W Smart AC adapter	**Dimensions** (H x W x D)	95.0 x 40.0 x 26.5 mm
	Weight	200 g +/- 10 g
	Not including power cord. Power cord varies by country.	
	Input	100 to 240 VAC
	Input Efficiency	87.74 % at 115 Vac and 88.4 % at 230Vac

Not all configuration components are available in all regions/countries.
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	Input frequency range	48 ~ 63 Hz
	Input AC current	Max. 1.4 A at 90 Vac
Output	**Output power**	45 W
	DC output	19.5 V
	Hold-up time	5 ms at 115 Vac input
	Output current limit	<8.0A
Connector	C6, 4.5mm barrel type	
Environmental Design	**Operating temperature**	32°F to 95°F (0°C to 35°C)
	Non-operating (storage) temperature	-4°F to 185°F (-20°C to 85°C)
	Altitude	0 to 16,400 ft (0 to 5000m)
	Humidity	20% to 95%
	Storage Humidity	10% to 95%
EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives. Worldwide safety standards – IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals – C–UL–US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF – over 200,000 hours at 25°C ambient condition.	

HP 65 W Smart AC adapter	**Dimensions** (H x W x D)	90.0 x 51 x 28.5 mm
	Weight	230 g +/- 10 g
	Not including power cord. Power cord varies by country.	
	Input	100 to 240 VAC
	Input Efficiency	87.74 % at 115 Vac and 88.4 % at 230Vac
	Input frequency range	48 ~ 63 Hz
	Input AC current	Max. 1.7 A at 90 Vac
Output	**Output power**	65 W
	DC output	19.5 V
	Hold-up time	5 ms at 115 Vac input
	Output current limit	<11.0 A
Connector	C6, 4.5mm barrel type	
Environmental Design	**Operating temperature**	32°F to 95°F (0°C to 35°C)
	Non-operating (storage) temperature	-4°F to 185°F (-20°C to 85°C)
	Altitude	0 to 16,400 ft (0 to 5000m)
	Humidity	20% to 95%
	Storage Humidity	10% to 95%
EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives. Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C–UL–US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.	

Not all configuration components are available in all regions/countries.
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HP EM 65 W Smart AC adapter	**Dimensions** (H x W x D)	102 x 55 x 30 mm	
	Weight	250 g +/- 10 g	
		Not including power cord. Power cord varies by country.	
	Input	100 to 240 VAC	
		Input Efficiency	87.74 % at 115 Vac and 88.4 % at 230Vac
		Input frequency range	48 ~ 63 Hz
		Input AC current	Max. 1.7 A at 90 Vac
	Output	**Output power**	65 W
		DC output	19.5 V
		Hold-up time	5 ms at 115 Vac input
		Output current limit	<11.0 A
	Connector	C6, 4.5mm barrel type	
	Environmental Design	**Operating temperature**	32°F to 95°F (0°C to 35°C)
		Non-operating (storage) temperature	-4°F to 185°F (-20°C to 85°C)
		Altitude	0 to 16,400 ft (0 to 5000m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives. Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.	

HP 3-cell Long Life Li-Ion (41 WHr)	**Dimensions** (H x W x D)	6.0 x 186.35 x 90.2 mm (0.236 x 7.33 x 3.55 inch)	
	Weight	0.19 kg (0.418 lb)	
	Cells/Type	3cell Lithium-Ion Polymer cell / 515974 Prismatic cell 496080	
	Energy	**Voltage**	11.55 V/11.4 V/11.34 V
		Amp-hour capacity	3.63 Ah/3.6 Ah/3.62 Ah
		Watt-hour capacity	41 Wh
	Temperature	**Operating (Charging)**	32° to 113° F (0° to 45° C)
		Operating (Discharging)	14° to 122° F (-10° to 60° C)
	Optional Travel Battery Available	No	

Not all configuration components are available in all regions/countries.
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Technical Specifications

FINGERPRINT SENSOR

Model	Elan eFSA80ST touch sensor
Mobile Voltage Operation	2.65 V to 3.6 V
Operating Temperature	32° to 95° F (0° to 35° C)
Current Consumption Image	50 mA peak
Low Latency Wait for Finger	<900 uA
Capture Rate	20 cm/sec
ESD Resistance	IEC 61000-4-2 (+15KV)
Detection Matrix	508 dpi / 4 x 4 mm sensor area
FRR (False Reject Rate) / FAR (False Acceptance Rate)	FRR ~ 2% @ 1:50 K FAR

Not all configuration components are available in all regions/countries.
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QuickSpecs

Options and Accessories (sold separately and availability may vary by country)

Category	Description	Part Number
Cases	HP Essential Top Load Case	H2W17AA
	HP Essential Backpack (up to 15.6")	H1D24AA
	HP Essential Messenger Case (up to 17.3")	H1D25AA
Docking	HP 3005pr USB3 Port Replicator	Y4H06AA
	HP USB Travel Dock	T0K30AA
	HP USB-C Universal Dock	1MK33AA
	HP USB-C Universal Dock NF (non-flash)	3DV65AA
	HP USB-C Dock G5	5TW10AA
	HP USB-C/A Universal Dock G2	5TW13AA
	HP USB-C Mini Dock	1PM64AA
Input/Output	HP USB Essential Keyboard and Mouse	H6L29AA
	HP Ultra Mobile Wireless Mouse	H6F25AA
	HP Comfort Grip Wireless Mouse	H2L63AA
	HP 3-Button USB Laser Mouse	H4B81AA
	HP USB Travel Mouse	G1K28AA
	HP HDMI to DVI Adapter	F5A28AA
	HP HDMI to VGA Adapter	H4F02AA
	HP USB-C to VGA Adapter	N9K76AA
	HP USB-C to HDMI 2.0 Adapter	1WC36AA
	HP Stereo USB Headset	T1A67AA
	HP Stereo 3.5mm Headset	T1A66AA
Power	HP 65W Smart AC Adapter	H6Y89AA
	HP 45W Smart Power Adapter (w/ 4.5mm to 7.5mm DC dongle)	H6Y88AA
	HP 45W Smart Power Adapter 2 prong -4.5mm (Japan only)	L6F60AA
	HP 65W 4.5mm non-EM AC Adapter (India only)	3FF84AA
Storage	HP Mobile USB DVDRW	F2B56AA
UCC	HP Conferencing Keyboard	K8P74AA
	HP UC Speaker Phone	4VW02AA

Summary of Changes

Date of change:	Version History:		Description of change:
February 18, 2020	From v1 to v2	Updated	Keyboard
February 27, 2020	From v2 to v3	Updated	Copyright and footnote for fingerprint sensor.
April 12, 2020	From v3 to v4	Updated	Weights and Ports sections
April 22, 2020	From v4 to v5	Updated	Networking / Communications section

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